

# Intel Platform Memory Operations

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## Intel Platform Memory Operations

### LPDDR3 System Validation Results:

Listed below are the results from a small sample of LPDDR3 Low power DRAMs tested on Intel reference mobile platforms based on 7<sup>th</sup> Gen Intel® Core™ Processor based on Mobile U-Processor Line (codename KabyLake). Providing this information as a guide to component performance with Intel® reference platforms. This testing is not intended to replace the normal OEM component qualification process. For results on specific Intel® motherboards or OEM production motherboards, please refer to the OEM's list of qualified memory suppliers.

Updated / New Part							
DRAM LPDDR3 178ball - Low Power 1866 (Memory Down)							
DRAM							
Supplier	Part Number	Package Density	Density Die	Package	Width	Die Revision	Date Code
Micron	MT52L256M32D1PF-107 WT:B	8Gb	8Gb	SDP	x32	B	1536
Micron	MT52L512M32D2PF-107 WT:B	16Gb	8Gb	DDP	x32	B	1532
Micron	MT52L1G32D4PG-107 WT:B	32Gb	8Gb	QDP	x32	B	1533
Samsung	K4E8E324EB-EGCF	8Gb	8Gb	SDP	x32	B	1540
Samsung	K4E6E304EB-EGCF	16Gb	8Gb	DDP	x32	B	1541
Samsung	K4EBE304EB-EGCF	32Gb	8Gb	QDP	x32	B	1543
Samsung	*K4E4E324EE-EGCF	4Gb	4Gb	SDP	x32	E	1440
Samsung	*K4E8E304EE-EGCF	8Gb	4Gb	DDP	x32	E	1425
Samsung	*K4E6E304EE-EGCF	16Gb	4Gb	QDP	x32	E	1419
SK Hynix	H9CCNNN8GTALAR-NUD	8Gb	8Gb	SDP	x32	A	1623
SK Hynix	H9CCNNNBJTALAR-NUD	16Gb	8Gb	DDP	x32	A	1623
SK Hynix	H9CCNNNCLTALAR-NUD	32Gb	8Gb	QDP	x32	A	1622
SK Hynix	*H9CCNNN8GTMLAR-NUD	8Gb	8Gb	SDP	x32	M	1438
SK Hynix	*H9CCNNNBJTMLAR-NUD	16Gb	8Gb	DDP	x32	M	1448
SK Hynix	*H9CCNNNCLTMLAR-NUD	32Gb	8Gb	QDP	x32	M	1448

Updated on Nov 1, 2016 \* Validated on BDW-U

**LPDDR3 253ball - 1866 ATE Validation Results: See complete list on next page**

## Intel Platform Memory Operations

### LPDDR3 253ball - 1866 ATE Validation Results:

Listed below are the results from a small sample of LPDDR3 1866 Low power 253ball DRAMs tested on ATE only.

DRAM LPDDR3 253ball - Low Power 1866 (Memory Down)							
DRAM							
Supplier	Part Number	Package Density	Density Die	Package	Width	Die Revision	Date Code
Micron	MT52L256M64D2PP-107 WT:B	16Gb	8Gb	DDP	x64	B	1604
Micron	MT52L512M64D4PQ-107 WT:B	32Gb	8Gb	QDP	x64	B	1602
Samsung	K3QF1F10EM-AGCF	8Gb	4Gb	DDP	x64	E	1435
Samsung	K3QF2F20EM-AGCF	16Gb	4Gb	QDP	x64	E	1429
Samsung	K3QF3F30BM-AGCF	16Gb	8Gb	DDP	x64	B	1620
Samsung	K3QF2F20EM-AGCF	32Gb	8Gb	QDP	x64	B	1619
SK Hynix	H9CCNNNBKTMLBR-NUD	16Gb	8Gb	DDP	x64	M	1508
SK Hynix	H9CCNNNCPTMLBR-NUD	32Gb	8Gb	QDP	x64	M	1508

Updated on Nov 1, 2016

